

7-10 OCTOBER 2024 | RONALD REAGAN BUILDING & INTERNATIONAL TRADE CENTER

6G and Emerging Technologies

Antennas, Propagation and RF Design

Electric Vehicles, Vehicular Electronics, and Intelligent Transportation

IoV, IoT, M2M, Sensor Networks, and Ad-Hoc Networking

Machine Learning for Communications

Protocols, Security and Services for Wireless Networks

Radio Access Technologies and Heterogenous Networks

Satellite Networks, Positioning Technologies, Localization and Navigation

Spectrum Management, Spectrum Sharing and Green Communications

Transmission Technologies and Communication Theory

Vehicular Communications, Unmanned Vehicle Communications, Vehicular Networks and Telematics

IMPORTANT DATES

SUBMIT PAPERS BY

April 22, 2024

ACCEPTANCE BY

July 8, 2024

FINAL PAPERS BY

August 5, 2024

vtc2024fall.trackchair.com



VTC2024-Fall will be held in Washington DC, USA. This semi-annual flagship conference of IEEE Vehicular Technology Society will bring together individuals from academia, government, and industry to discuss and exchange ideas in the fields of wireless, mobile, and vehicular technology.

VTC2024-Fall will feature world-class plenary speakers, tutorials, technical as well as application sessions, and an innovative Industry Track, which will feature panels and presentations with industry leaders sharing their perspectives on the latest technologies.

Prospective authors are encouraged to submit full papers through the conference website or directly in TrackChair: vtc2024fall.trackchair.com. Prospective authors are invited to submit 5-page, original, and unpublished full papers. A full paper can be up to 7 pages in length, just note that papers longer than 5 pages will require the purchase of additional page charges at the time of registration and final paper submission.

The conference also invites submissions of cutting-edge workshop proposals to complement the technical program of the 100th edition of VTC. Workshops provide invaluable opportunities for researchers and industry practitioners to share their state-of-the-art research and development results in areas of particular interest. More information on the workshop submission procedure can be found at the conference web site.

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